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!!!The present invention relates to an electronic endoscope which is an insertion portion insertion type, and more specifically, relates to an electronic endoscope which is a digital camera and which records an image picked up by a solid-state imaging device in a memory and in which a display portion is capable of displaying the recorded image. A solid-state imaging device is formed by a very large number of picture elements. The picture elements are arranged as a matrix and the region in which the picture elements are formed is determined according to the size of an area that a light receiving portion is included and the amount of light incident from a light source. A solid-state imaging device is classified into two types, a CCD (charge-coupled device) type and a MOS (metal oxide semiconductor) type. The CCD type has many defects. The number of defects is three times as many as that of the MOS type. The defects are as follows. Namely, the defects are static defects generated in the fabrication process, defects caused by radiation of radiation from an environment at a high temperature in the fabrication process, and defects caused by accumulated electric charge of the device. The defects are all electric charge accumulated in a channel. Since it is very important to record the image in good condition, it is required to remove the defect electric charge which is generated in a channel in the manufacturing process and which is changed by various factors. The defect electric charge is removed by applying a strong reverse bias voltage to an area having the defect. It is said that it is possible to remove the defect electric charge generated in the manufacturing process by reducing the strength of the reverse bias voltage. It is reported that it is possible to remove most of the defect electric charge by applying a reverse bias voltage of -10 V to the defect area. In the case of an endoscope of the digital type, a method of removing the defect electric charge of the solid-state imaging device in the vicinity of the light source in the manufacturing process of the endoscope has been used. When the reverse bias voltage is applied to the solid-state imaging device, the light source in the vicinity of the solid-state imaging device cannot provide a sufficiently strong light for pick-up and consequently, it is necessary to use an auxiliary light source which is placed apart from the solid-state imaging device. The diameter of the endoscope becomes larger as the auxiliary light source is larger and the movement of the endoscope becomes cumbersome. It is therefore an 82157476af

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